

**Product / Package Information**

Package	SOIC_N
Body Size	150 mils
Lead Count	8
Terminal Finish	100 Sn
MS Number	MS000506C

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	3.64E-02	87.7	877000	51.15		511478
Thermosets	Phenol Resin	Proprietary	1.66E-03	4.0	40000	2.33		23329
Thermosets	Epoxy Resin 1	Proprietary	1.25E-03	3.0	30000	1.75		17496
Thermosets	Epoxy Resin 2	Proprietary	1.45E-03	3.5	35000	2.04		20412
Others	Others	Proprietary	6.23E-04	1.5	15000	0.87		8748
Other inorganic materials	Carbon Black	1333-86-4	1.25E-04	0.3	3000	0.17		1750
Subtotal			4.15 E-02	100.00	1000000	58.32		583214

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	2.34 E-02	97.5	975000	32.88		328762
Copper & its alloys	Iron	7439-89-6	5.64 E-04	2.35	23500	0.79		7924
Copper & its alloys	Zinc	7440-66-6	2.88 E-05	0.12	1200	0.04		405
Copper & its alloys	Phosphorus	7723-14-0	7.21 E-06	0.03	300	0.01		101
Subtotal			2.40 E-02	100.00	1000000	33.72		337192

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.43E-04	100.0	1000000	0.34		3406

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	1.37 E-03	100.0	1000000	1.92		19186

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	2.97 E-04	99.00	990000	0.42		4169
Precious Metals	Palladium	7440-05-3	3.00 E-06	1.00	10000	0.004		42
Subtotal			3.00 E-04	100.0	1000000	0.42		4212

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	2.63 E-03	100.0	1000000	3.69		36925

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	8.70 E-04	77.00	770000	1.22		12216
Other organic materials	Acrylic resin	Proprietary	7.91 E-05	7.00	70000	0.11		1111
Other organic materials	Acrylate	Proprietary	6.22 E-05	5.50	55000	0.09		873
Other organic materials	Polybutadiene derivative	Proprietary	5.09 E-05	4.50	45000	0.07		714
Thermoset	Epoxy resin	Proprietary	2.83 E-05	2.50	25000	0.04		397
Other organic materials	Butadiene Copolymer	Proprietary	1.70 E-05	1.50	15000	0.02		238
Others	Additive	Proprietary	1.70 E-05	1.50	15000	0.02		238
Others	Peroxide	Proprietary	5.65 E-06	0.50	5000	0.008		79
Subtotal			1.13 E-03	100.0	1000000	1.59		15865

<b>Package Totals</b>			<b>Weight (g)</b> 7.12 E-02			<b>Percentage (%)</b> 100		<b>PPM</b> 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary



Product / Package Information	
Package	SOIC_N
Body Size	150 mils
Lead Count	8
Terminal Finish	NiPdAu

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

### Materials Declaration

#### Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.09 E-02	87.7	877000	47.10	470965
Thermosets	Epoxy Resin	Proprietary	2.33 E-03	5.0	50000	2.69	26851
Thermosets	Phenol Resin	Proprietary	2.33 E-03	5.0	50000	2.69	26851
Thermosets	Epoxy Cresol Novolac	29690-82-2	9.33 E-04	2.0	20000	1.07	10740
Other inorganic materials	Carbon Black	1333-86-3	1.40 E-04	0.3	3000	0.16	1611
Subtotal			4.66 E-02	100.0	1000000	54	537018

#### Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.34 E-02	97.5	975000	38.41	384050
Copper & its alloys	Iron	7439-89-6	8.04 E-04	2.35	23500	0.93	9257
Copper & its alloys	Zinc	7440-66-6	4.11 E-05	0.12	1200	0.05	473
Copper & its alloys	Phosphorus	7723-14-0	1.03 E-05	0.03	300	0.01	118
Subtotal			3.42 E-02	100	1000000	39	393898

#### Internal/External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	6.23 E-04	97.27	972697	0.72	7168
Precious metals	Palladium	7440-05-3	1.45 E-05	2.26	22621	0.02	167
Precious metals	Gold	7440-57-5	3.00 E-06	0.47	4683	0.00	35
Subtotal			6.40 E-04	100.00	1000000	0.74	7369

#### Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.20 E-04	99.99	1000000	0.25	2533

#### Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.96 E-03	100	1000000	4.56	45596

#### Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.17 E-04	77.71	777100	1.06	10558
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-96-5	3.67 E-05	3.11	31100	0.04	423
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	3.67 E-05	3.11	31100	0.04	423
Other organic materials	Butyrolactone, gamma-	96-48-0	3.67 E-05	3.11	31100	0.04	423
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	3.67 E-05	3.11	31100	0.04	423
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.67 E-05	3.11	31100	0.04	423
Other organic materials	Organosilane	TS ref# 10001	3.67 E-05	3.11	31100	0.04	423
Other inorganic materials	Copper(II) oxide	1317-38-0	3.67 E-05	3.11	31100	0.04	423
Other organic materials	Epoxy resin modifier	TS ref# 10038	6.14 E-06	0.52	5200	0.007	71
Subtotal			1.18 E-03	100	1000000	1.36	13587

Package Totals	Weight (g)	Percentage (%)	PPM
	8.69 E-02	100	1000000

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**Product / Package Information**

Package	SOIC_N
Body Size	150 mils
Lead Count	8
Terminal Finish	SnPb

**Environmental Information**

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.35 E-02	80.7	807000	47.06	470648
Thermosets	Epoxy resin	Proprietary	4.15 E-03	10.0	100000	5.83	58321
Thermosets	Phenol Novolac	9003-35-4	1.25 E-03	3.0	30000	1.75	17496
Thermosets	Brominated Resin	68541-56-0	1.04 E-03	2.5	25000	1.46	14580
Other inorganic materials	Antimony Trioxide	1309-64-4	8.31 E-04	2.0	20000	1.17	11664
Thermosets	Phenol resin	Proprietary	6.23 E-04	1.5	15000	0.87	8748
Other inorganic materials	Carbon Black	1333-86-4	1.25 E-04	0.3	3000	0.17	1750
Subtotal			4.15 E-02	100.0	1000000	58.32	583208

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.34 E-02	97.57	975706	32.90	329007
Copper & its alloys	Iron	7439-89-6	5.47 E-04	2.28	22789	0.77	7684
Copper & its alloys	Zinc	7440-66-6	3.03 E-05	0.13	1263	0.04	426
Copper & its alloys	Phosphorus	7723-14-0	5.82 E-06	0.02	242	0.01	82
Subtotal			2.40 E-02	100.00	1000000	33.72	337199

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.43 E-04	100.0	1000000	0.34	3406

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.16 E-03	85.0	850000	1.63	16308
Tin & its alloys	Lead	7439-92-1	2.05 E-04	15.0	150000	0.29	2878
Subtotal			1.37 E-03	100.0	1000000	1.92	19186

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.00 E-04	99.99	1000000	0.42	4212

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.63 E-03	100.0	1000000	3.69	36925

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	8.78 E-04	77.71	777100	1.23	12329
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	3.51 E-05	3.11	31100	0.05	493
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	3.51 E-05	3.11	31100	0.05	493
Other organic materials	Butyrolactone, gamma-	96-48-0	3.51 E-05	3.11	31100	0.05	493
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	3.51 E-05	3.11	31100	0.05	493
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.51 E-05	3.11	31100	0.05	493
Other organic materials	Organosilane	TS ref# 10001	3.51 E-05	3.11	31100	0.05	493
Other inorganic materials	Copper(II) oxide	1317-38-0	3.51 E-05	3.11	31100	0.05	493
Other organic materials	Epoxy resin modifier	TS ref# 10038	5.88 E-06	0.52	5200	0.01	82
Subtotal			1.13 E-03	100.00	1000000	1.59	15865

Package Totals	Weight (g)	Percentage (%)	PPM
	7.12 E-02	100.00	1000000

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